

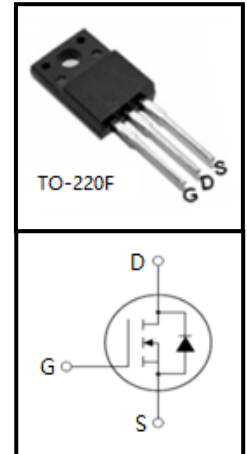
## 500V N-Channel MOSFET

### FEATURES

- Fast switching
- 100% avalanche tested
- Improved dv/dt capability

### APPLICATIONS

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)



### Device Marking and Package Information

Device	Package	Marking
CS20N50FF	TO-220F	CS20N50FF

### Absolute Maximum Ratings $T_C = 25^\circ\text{C}$ , unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-Source Voltage ( $V_{GS} = 0V$ )	$V_{DSS}$	500	V
Continuous Drain Current	$I_D$	20	A
Pulsed Drain Current (note1)	$I_{DM}$	80	A
Gate-Source Voltage	$V_{GSS}$	$\pm 30$	V
Single Pulse Avalanche Energy (note2)	$E_{AS}$	650	mJ
Avalanche Current (note1)	$I_{AS}$	11.4	A
Repetitive Avalanche Energy (note1)	$E_{AR}$	2.6	mJ
Power Dissipation ( $T_C = 25^\circ\text{C}$ )	$P_D$	39	W
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	-55~+150	$^\circ\text{C}$

### Thermal Resistance

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	$R_{thJC}$	3.2	$^\circ\text{C/W}$
Thermal Resistance, Junction-to-Ambient	$R_{thJA}$	62.5	

**Specifications**  $T_J = 25^{\circ}\text{C}$ , unless otherwise noted

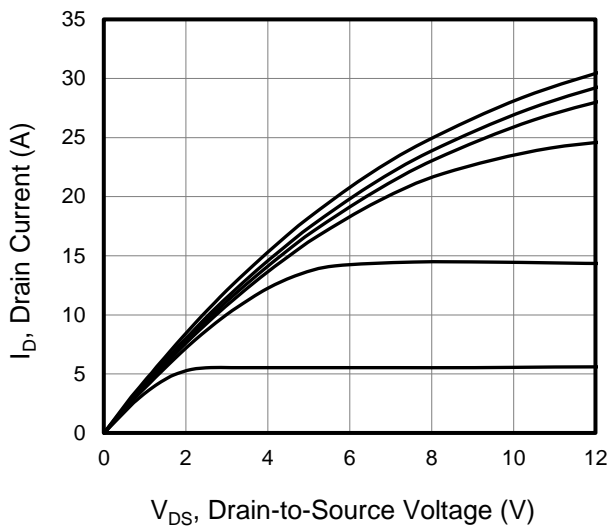
Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
Static						
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	500	--	--	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 500V, V <sub>GS</sub> = 0V, T <sub>J</sub> = 25°C	--	--	1	μA
Gate-Source Leakage	I <sub>GSS</sub>	V <sub>GS</sub> = ±30V	--	--	±100	nA
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	3.0	--	4.0	V
Drain-Source On-Resistance (Note3)	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 10A	--	0.21	0.27	Ω
Dynamic						
Input Capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V, V <sub>DS</sub> = 25V, f = 1.0MHz	--	2707	--	pF
Output Capacitance	C <sub>oss</sub>		--	292	--	
Reverse Transfer Capacitance	C <sub>rss</sub>		--	10.5	--	
Internal Gate Resistance	R <sub>g</sub>		--	1.2	--	Ω
Total Gate Charge	Q <sub>g</sub>	V <sub>DD</sub> = 400V, I <sub>D</sub> = 20A, V <sub>GS</sub> = 10V	--	49	--	nC
Gate-Source Charge	Q <sub>gs</sub>		--	13.3	--	
Gate-Drain Charge	Q <sub>gd</sub>		--	17.9	--	
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =250V, I <sub>D</sub> =20A, R <sub>G</sub> =25Ω	--	55.5	--	ns
Turn-on Rise Time	t <sub>r</sub>		--	32.7	--	
Turn-off Delay Time	t <sub>d(off)</sub>		--	226	--	
Turn-off Fall Time	t <sub>f</sub>		--	58.4	--	
Drain-Source Body Diode Characteristics						
Continuous Body Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C	--	--	20	A
Pulsed Diode Forward Current	I <sub>SM</sub>		--	--	80	
Body Diode Voltage	V <sub>SD</sub>	T <sub>J</sub> = 25°C, I <sub>SD</sub> = 10A, V <sub>GS</sub> = 0V	--	--	1.2	V
Reverse Recovery Time	t <sub>rr</sub>	VR=250V, I <sub>S</sub> = 20A, diF/dt = 100A/μs	--	318.6	--	ns
Reverse Recovery Charge	Q <sub>rr</sub>		--	4.5	--	μC

**Notes**

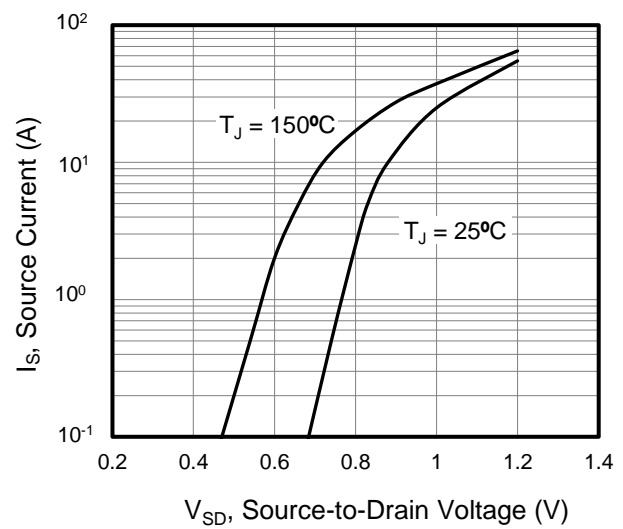
1. Repetitive Rating: Pulse width limited by maximum junction temperature
2.  $L=10mH, V_{DD} = 50V, R_G = 25\Omega$ , Starting  $T_J = 25^{\circ}\text{C}$
3. Pulse Test: Pulse width  $\leq 300\mu s$ , Duty Cycle  $\leq 1\%$

**Typical Characteristics**  $T_J = 25^\circ\text{C}$ , unless otherwise noted

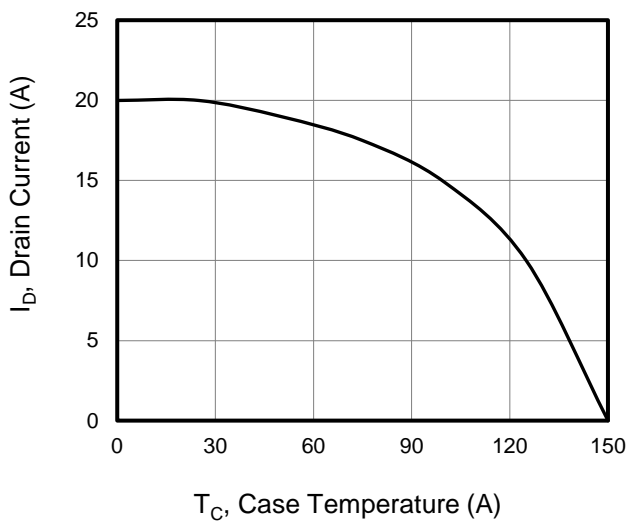
**Figure 1. Output Characteristics ( $T_J = 25^\circ\text{C}$ )**



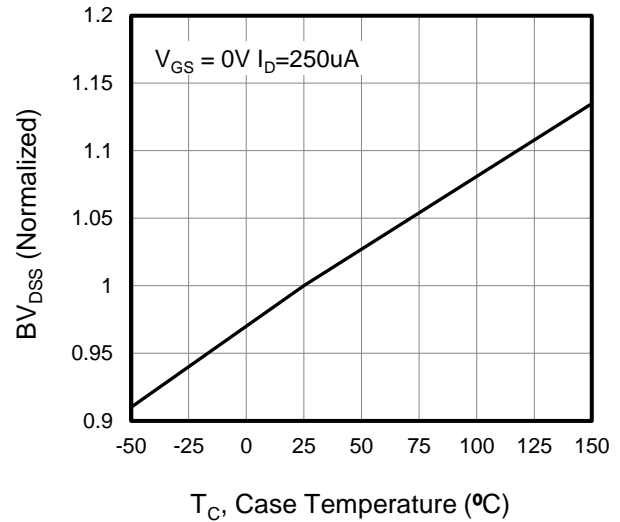
**Figure 2. Body Diode Forward Voltage**



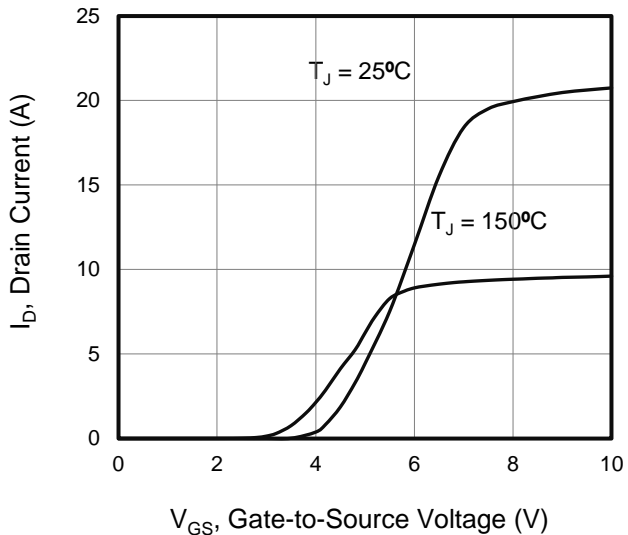
**Figure 3. Drain Current vs. Temperature**



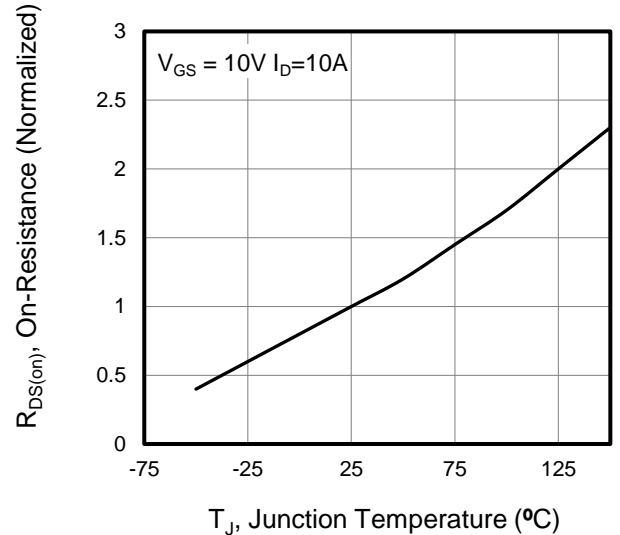
**Figure 4.  $BV_{DSS}$  Variation vs. Temperature**



**Figure 5. Transfer Characteristics**

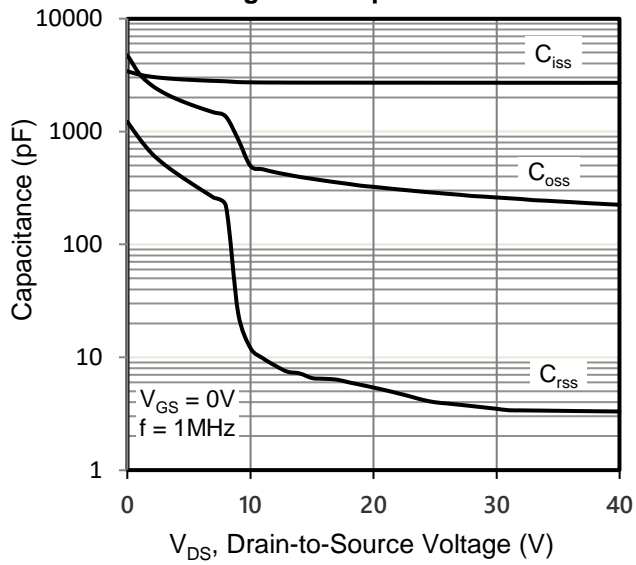


**Figure 6. On-Resistance vs. Temperature**

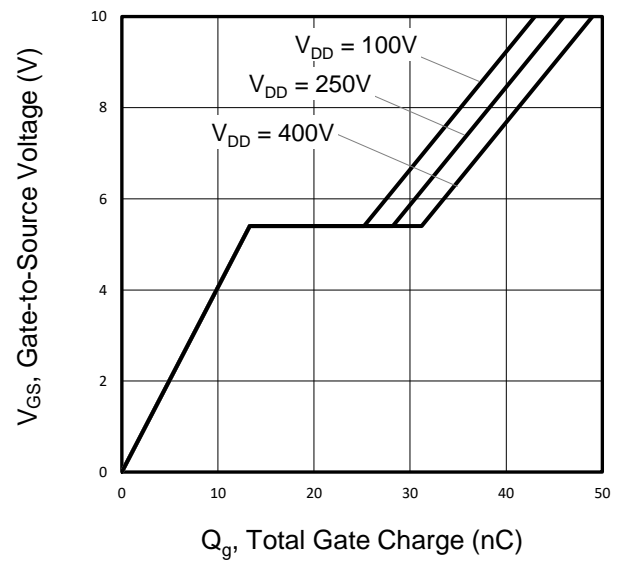


**Typical Characteristics**  $T_J = 25^\circ\text{C}$ , unless otherwise noted

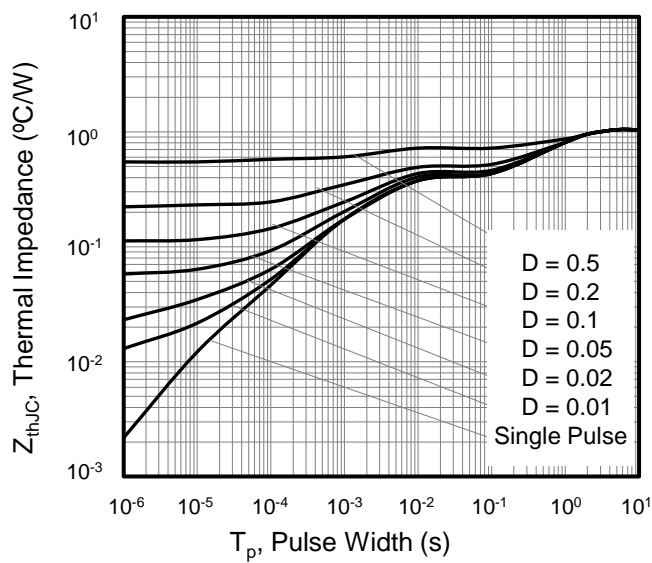
**Figure 7. Capacitance**

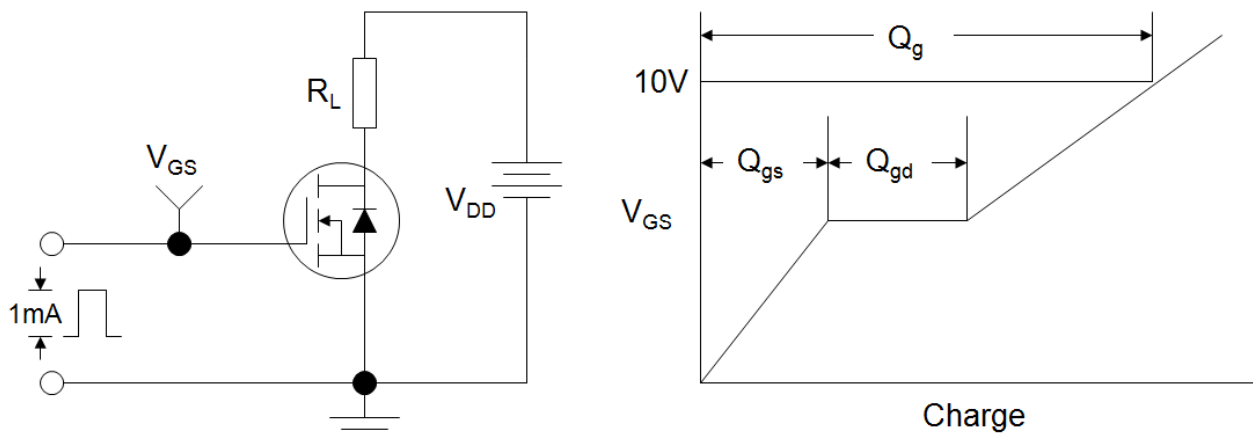
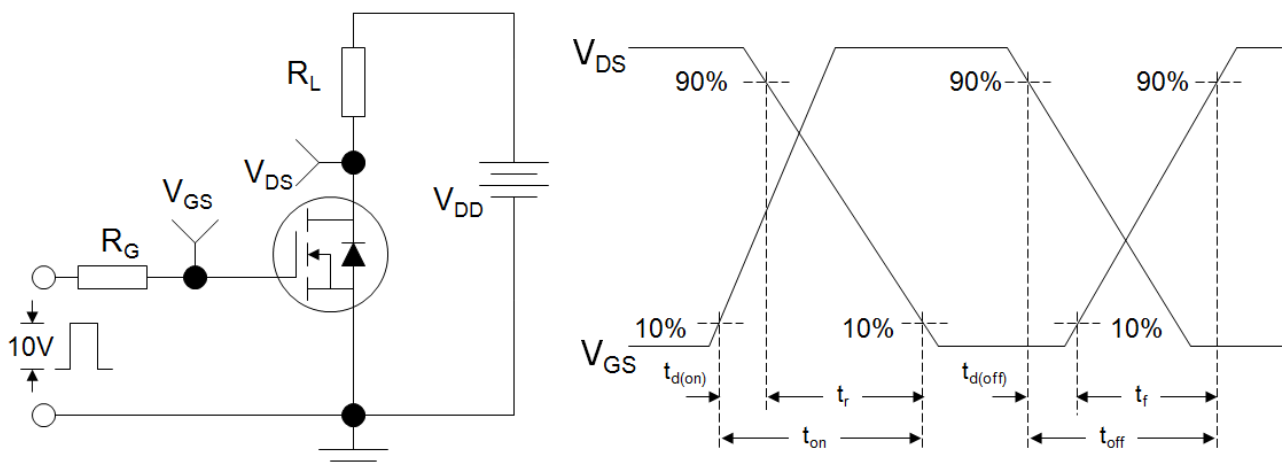
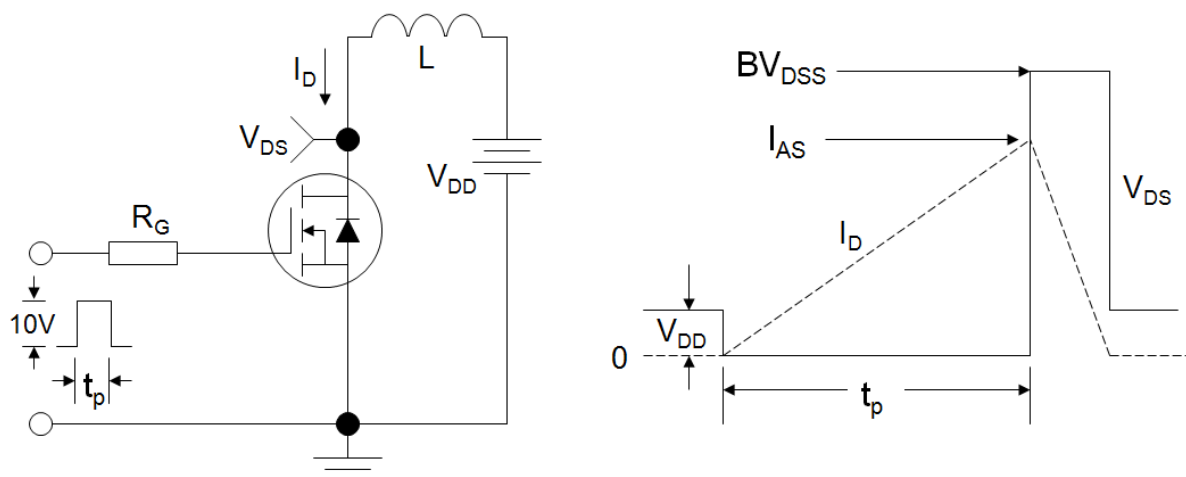


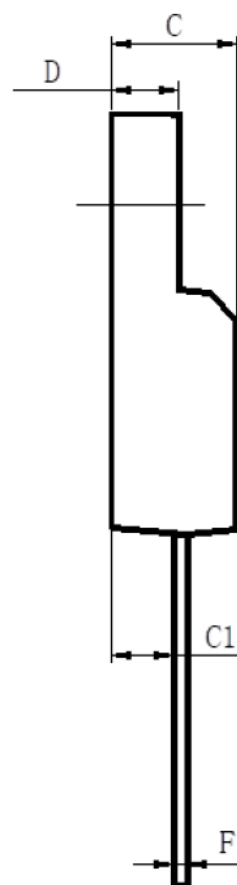
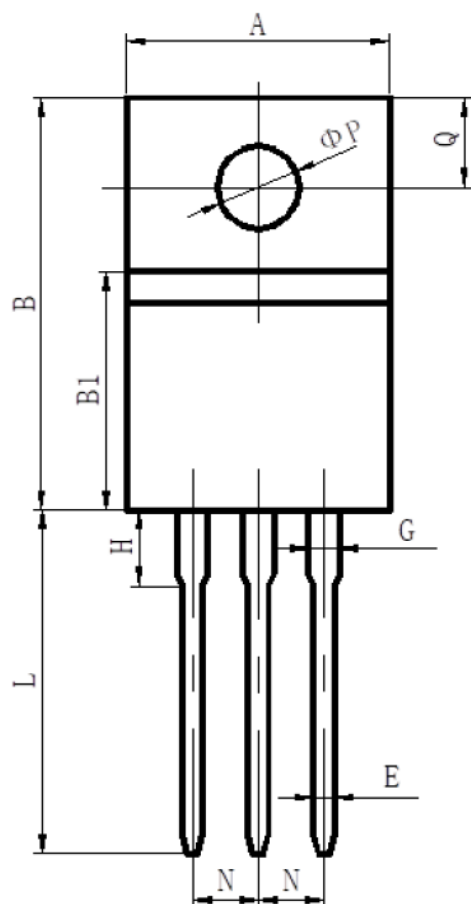
**Figure 8. Gate Charge**



**Figure 9. Transient Thermal Impedance**



**Figure A: Gate Charge Test Circuit and Waveform**

**Figure B: Resistive Switching Test Circuit and Waveform**

**Figure C: Unclamped Inductive Switching Test Circuit and Waveform**


**TO-220F**


SYMBOLS	MILLIMETERS	
	MIN	MAX
A	9.70	10.30
B	15.50	16.10
B1	8.99	9.39
C	4.40	4.80
C1	2.15	2.55
D	2.50	2.90
E	0.70	0.90
F	0.40	0.60
G	1.12	1.42
H	3.40	3.80
L	12.60	13.60
N	2.34	2.74
Q	3.15	3.55
$\Phi P$	3.00	3.30

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